

# SHINDENGEN

## HVX-2 Series Power MOSFET

N-Channel Enhancement type

**2SK2675  
(FP7W90HVX2)**

**900V 7A**

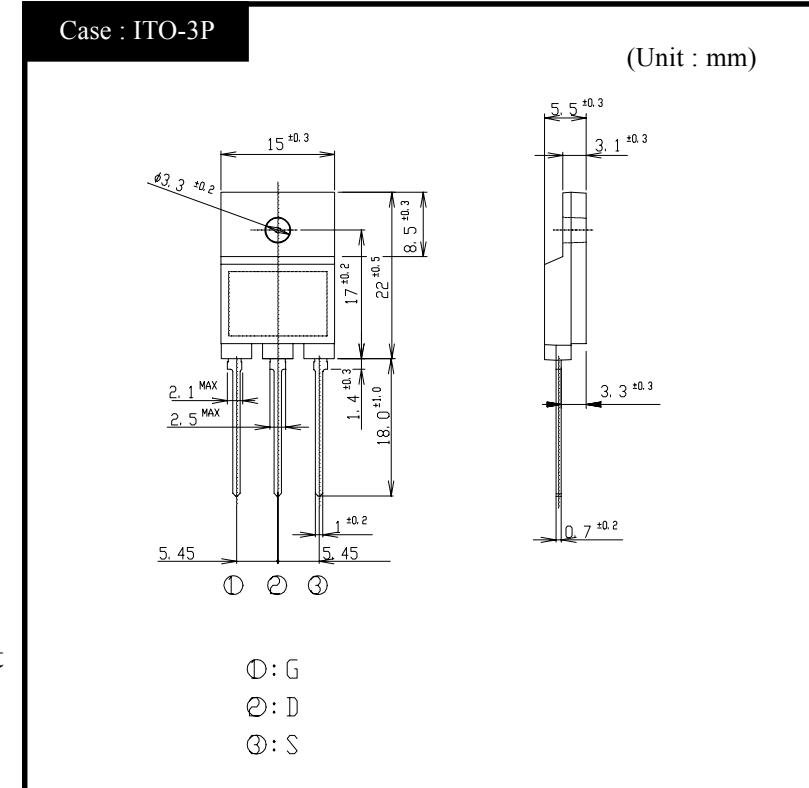
### FEATURES

- Input capacitance (C<sub>iss</sub>) is small.  
Especially, input capacitance at 0 bias is small.
- The static R<sub>d(on)</sub> is small.
- The switching time is fast.
- Avalanche resistance guaranteed.

### APPLICATION

- Switching power supply of AC 240V input
- High voltage power supply
- Inverter

### OUTLINE DIMENSIONS



### RATINGS

#### ● Absolute Maximum Ratings (T<sub>c</sub> = 25°C)

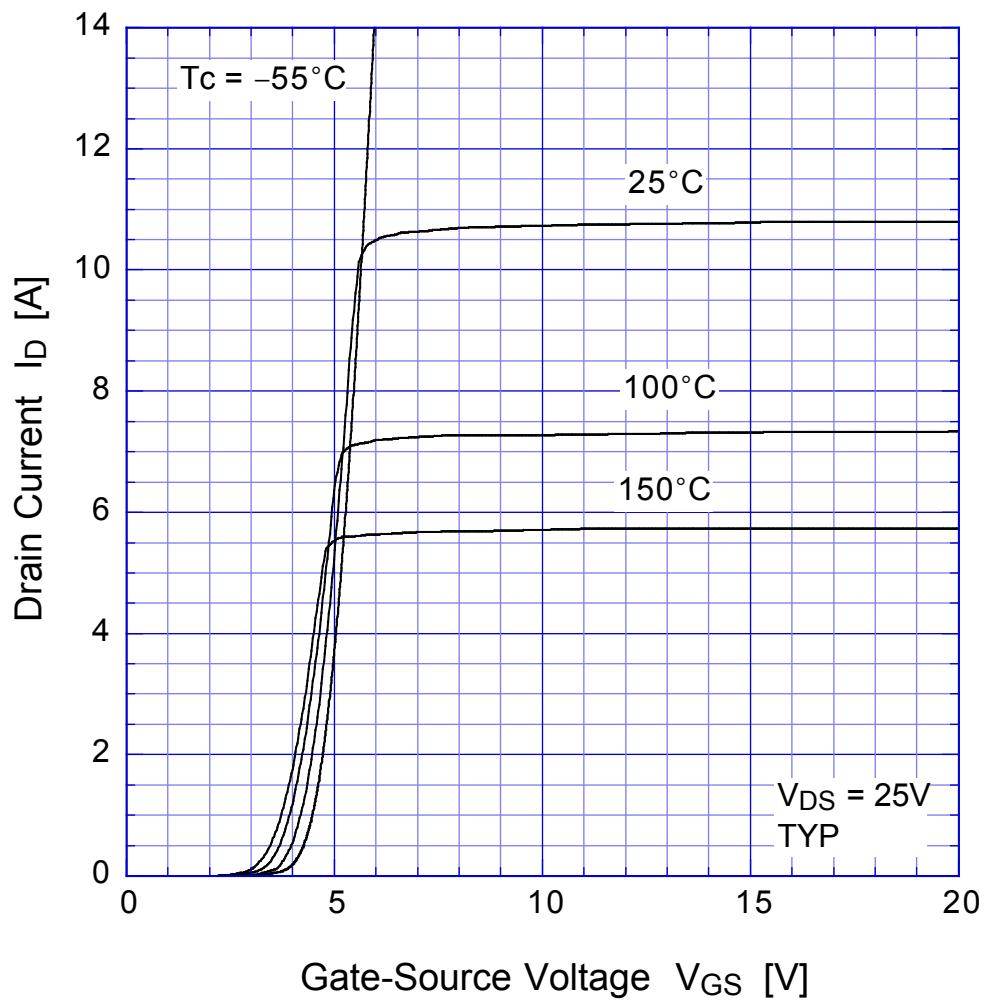
Item	Symbol	Conditions	Ratings	Unit
Storage Temperature	T <sub>stg</sub>		-55~150	°C
Channel Temperature	T <sub>ch</sub>		150	
Drain-Source Voltage	V <sub>DSS</sub>		900	V
Gate-Source Voltage	V <sub>GSS</sub>		±30	
Continuous Drain Current (DC)	I <sub>D</sub>		7	A
Continuous Drain Current (Peak)	I <sub>DP</sub>	Pulse width ≤ 10 μ s, Duty cycle ≤ 1/100	14	
Continuous Source Current (DC)	I <sub>S</sub>		7	
Total Power Dissipation	P <sub>T</sub>		55	W
Repetitive Avalanche Current	I <sub>AR</sub>	T <sub>ch</sub> = 150°C	7	A
Single Avalanche Energy	E <sub>AS</sub>	T <sub>ch</sub> = 25°C	160	mJ
Repetitive Avalanche Energy	E <sub>AR</sub>	T <sub>ch</sub> = 25°C	16	
Dielectric Strength	V <sub>dis</sub>	Terminals to case, AC 1 minute	2	kV
Mounting Torque	T <sub>OR</sub>	( Recommended torque : 0.5 N·m )	0.8	N·m

**●Electrical Characteristics T<sub>c</sub> = 25°C**

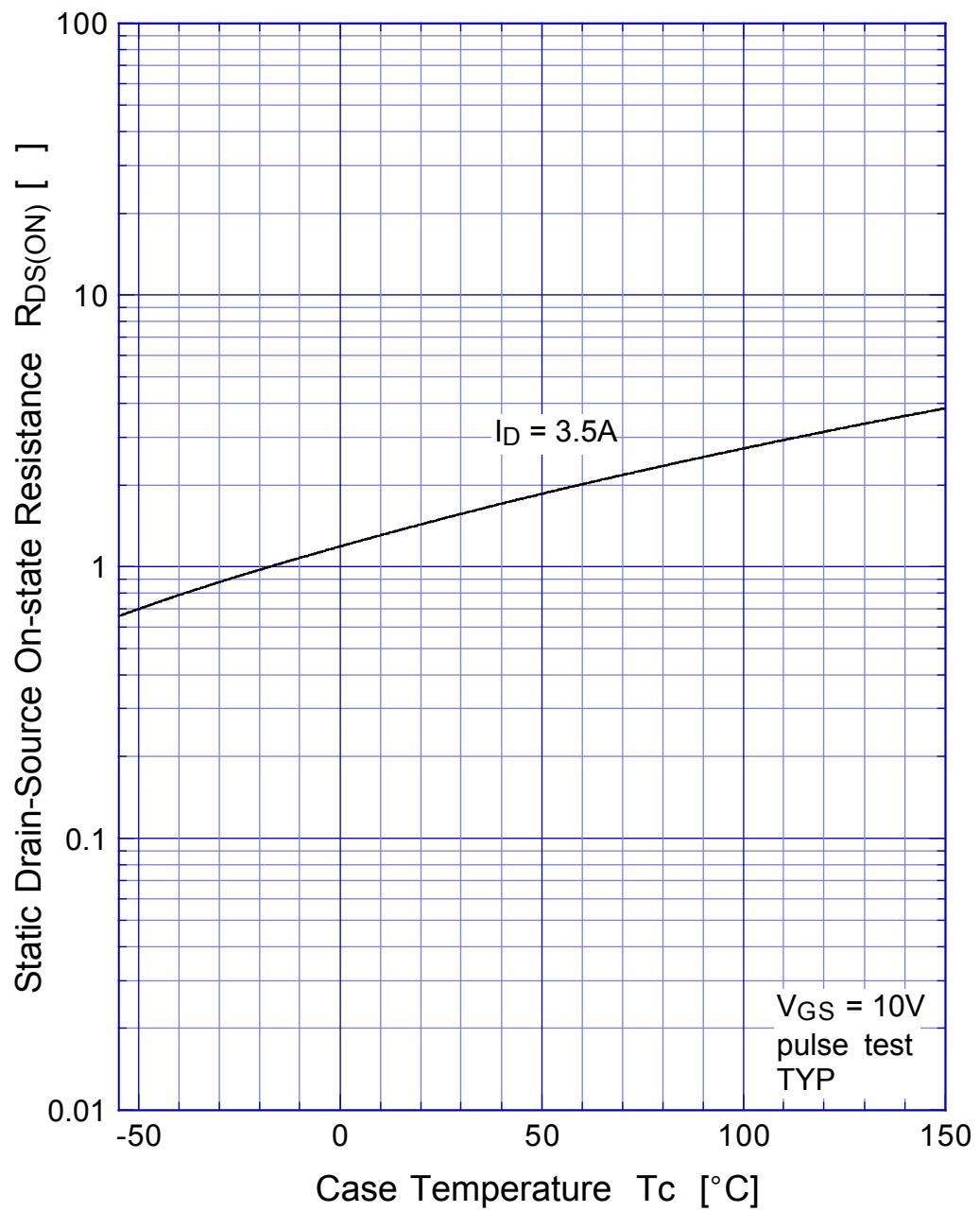
Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	ID = 1mA, V <sub>GS</sub> = 0V	900			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 900V, V <sub>GS</sub> = 0V			250	μ A
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±30V, V <sub>DS</sub> = 0V			±0.1	
Forward Transconductance	g <sub>fS</sub>	ID = 3.5A, V <sub>DS</sub> = 10V	3.6	6.0		S
Static Drain-Source On-state Resistance	R <sub>D(S)ON</sub>	ID = 3.5A, V <sub>GS</sub> = 10V		1.5	2.0	Ω
Gate Threshold Voltage	V <sub>TH</sub>	ID = 1mA, V <sub>DS</sub> = 10V	2.5	3.0	3.5	V
Source-Drain Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 3.5A, V <sub>GS</sub> = 0V			1.5	
Thermal Resistance	θ <sub>jc</sub>	junction to case			2.27	°C/W
Total Gate Charge	Q <sub>g</sub>	V <sub>DD</sub> = 400V, V <sub>GS</sub> = 10V, I <sub>D</sub> = 7A		63		nC
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1MHz		1450		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			37		
Output Capacitance	C <sub>oss</sub>			150		
Turn-On Time	t <sub>on</sub>	I <sub>D</sub> = 3.5A, R <sub>L</sub> = 43Ω, V <sub>GS</sub> = 10V		95	170	ns
Turn-Off Time	t <sub>off</sub>			330	560	

# 2SK2675

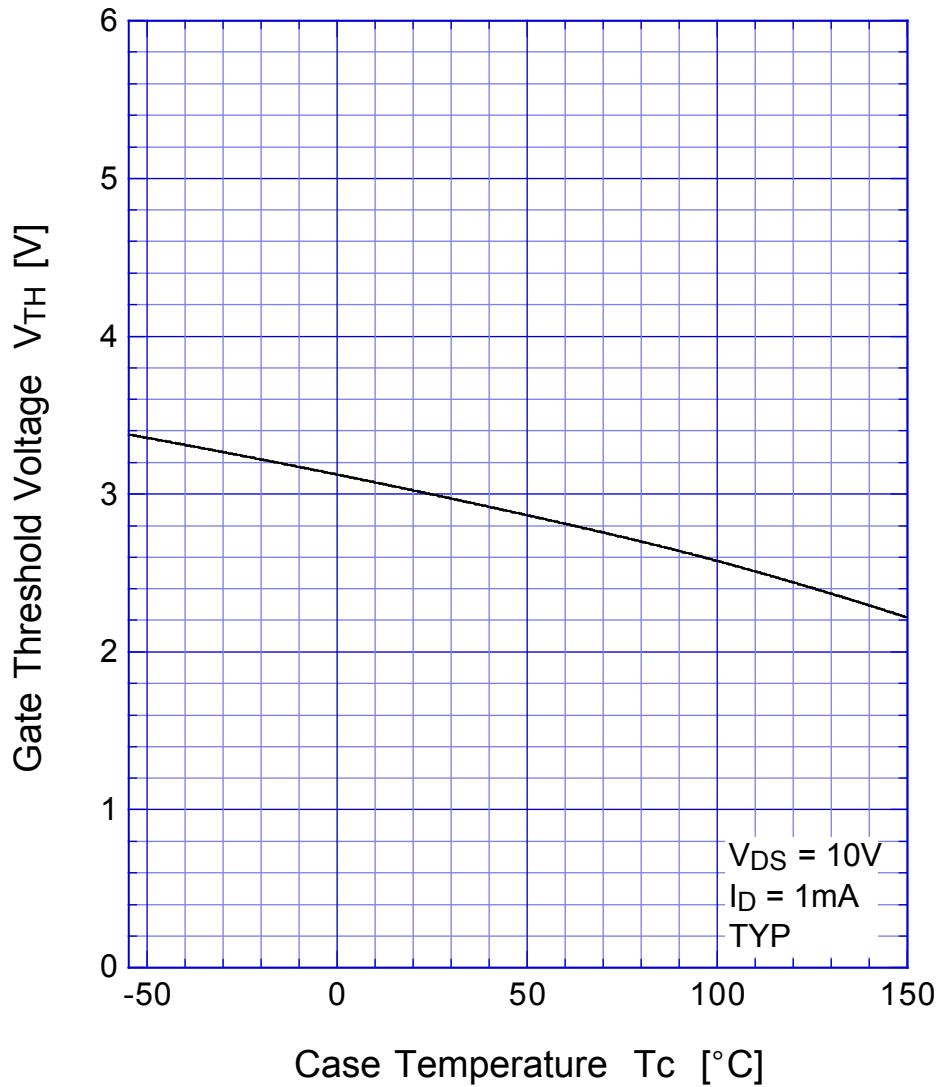
## Transfer Characteristics



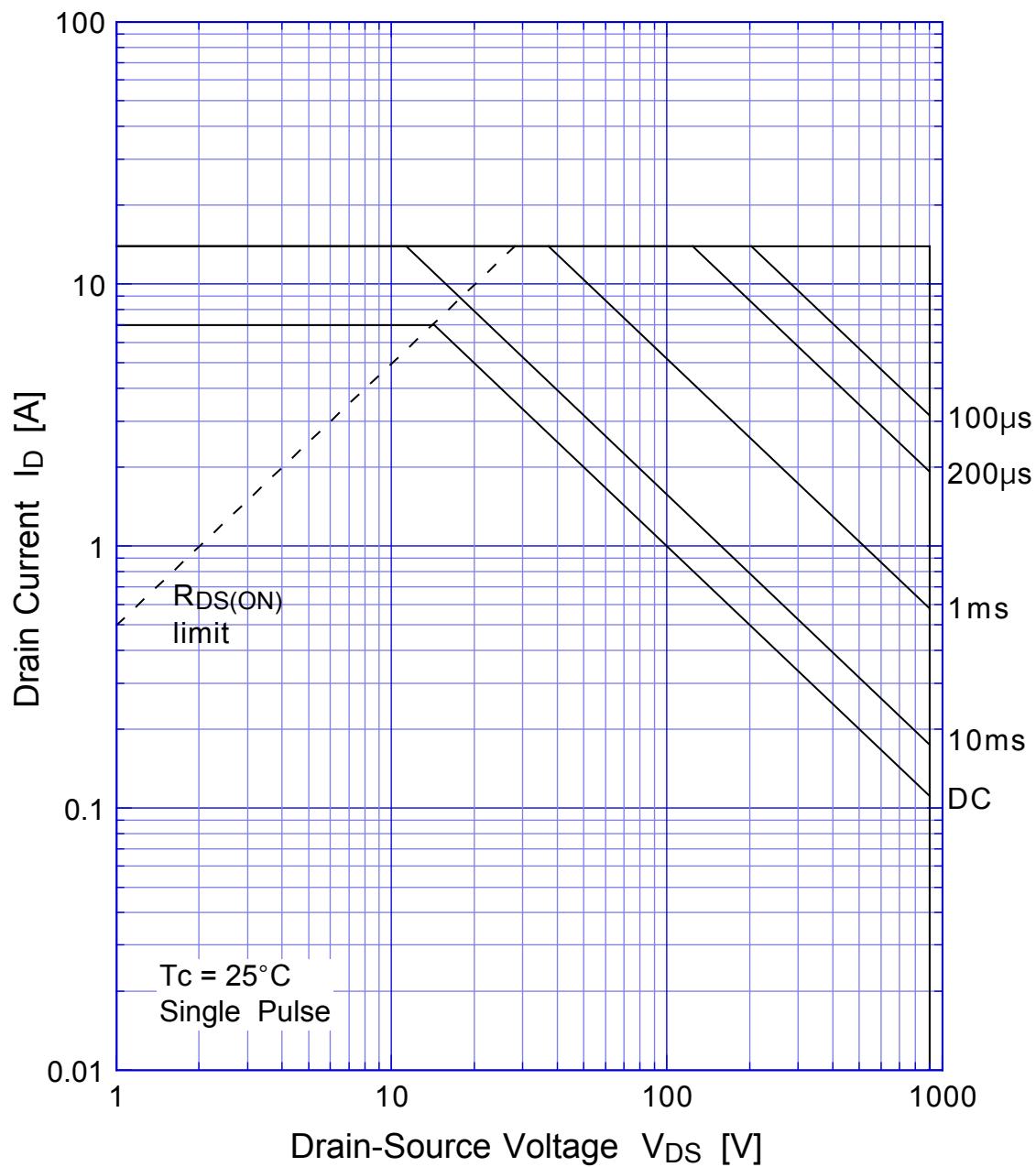
## 2SK2675 Static Drain-Source On-state Resistance



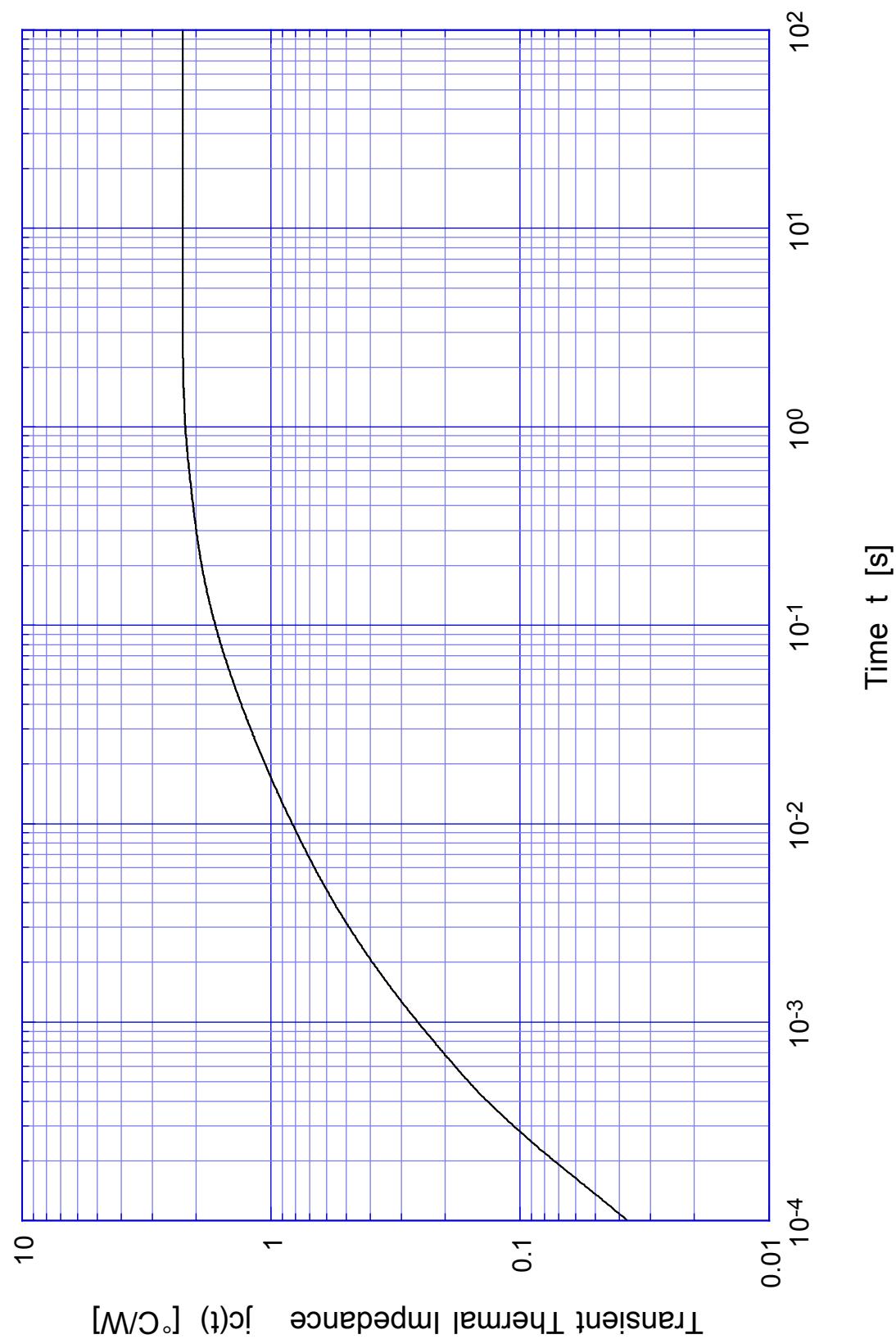
## **2SK2675      Gate Threshold Voltage**



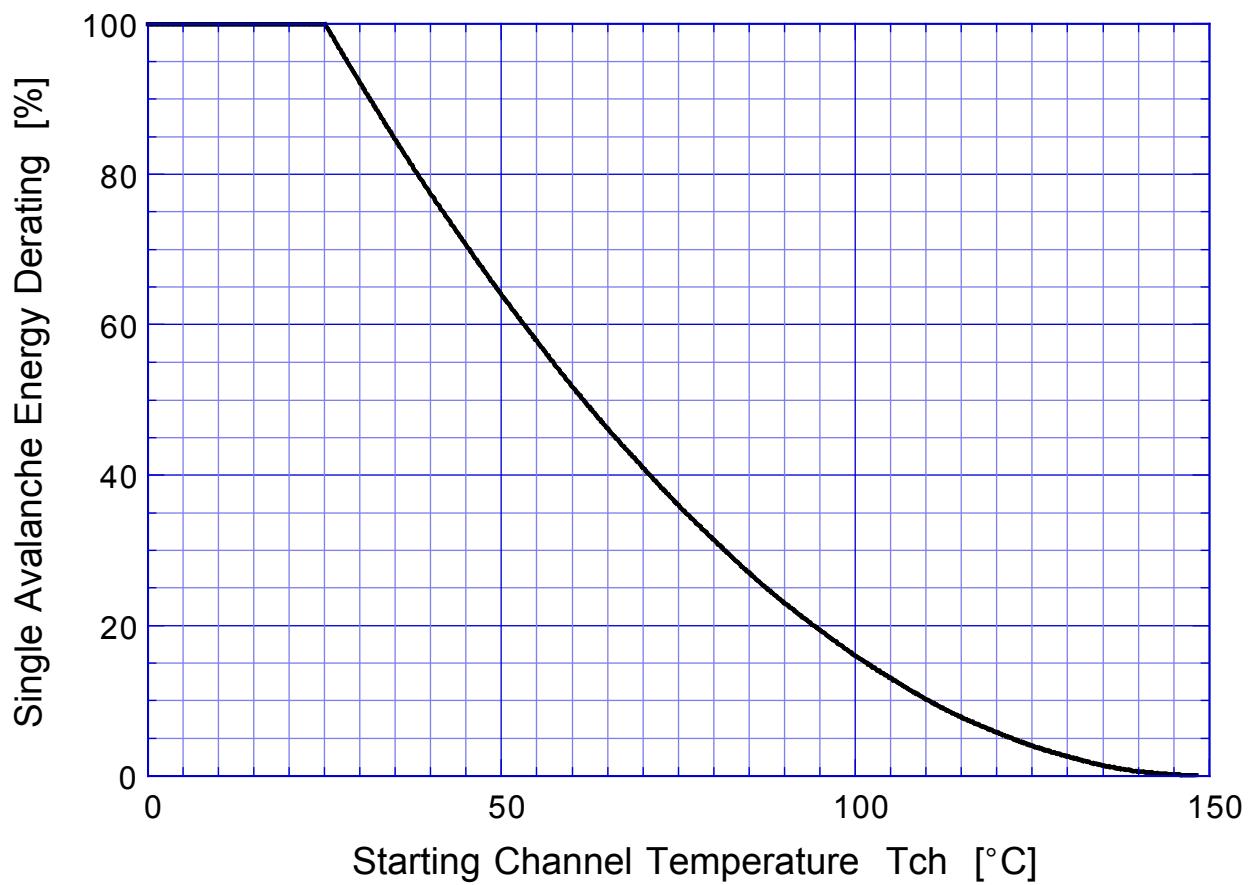
## 2SK2675 Safe Operating Area



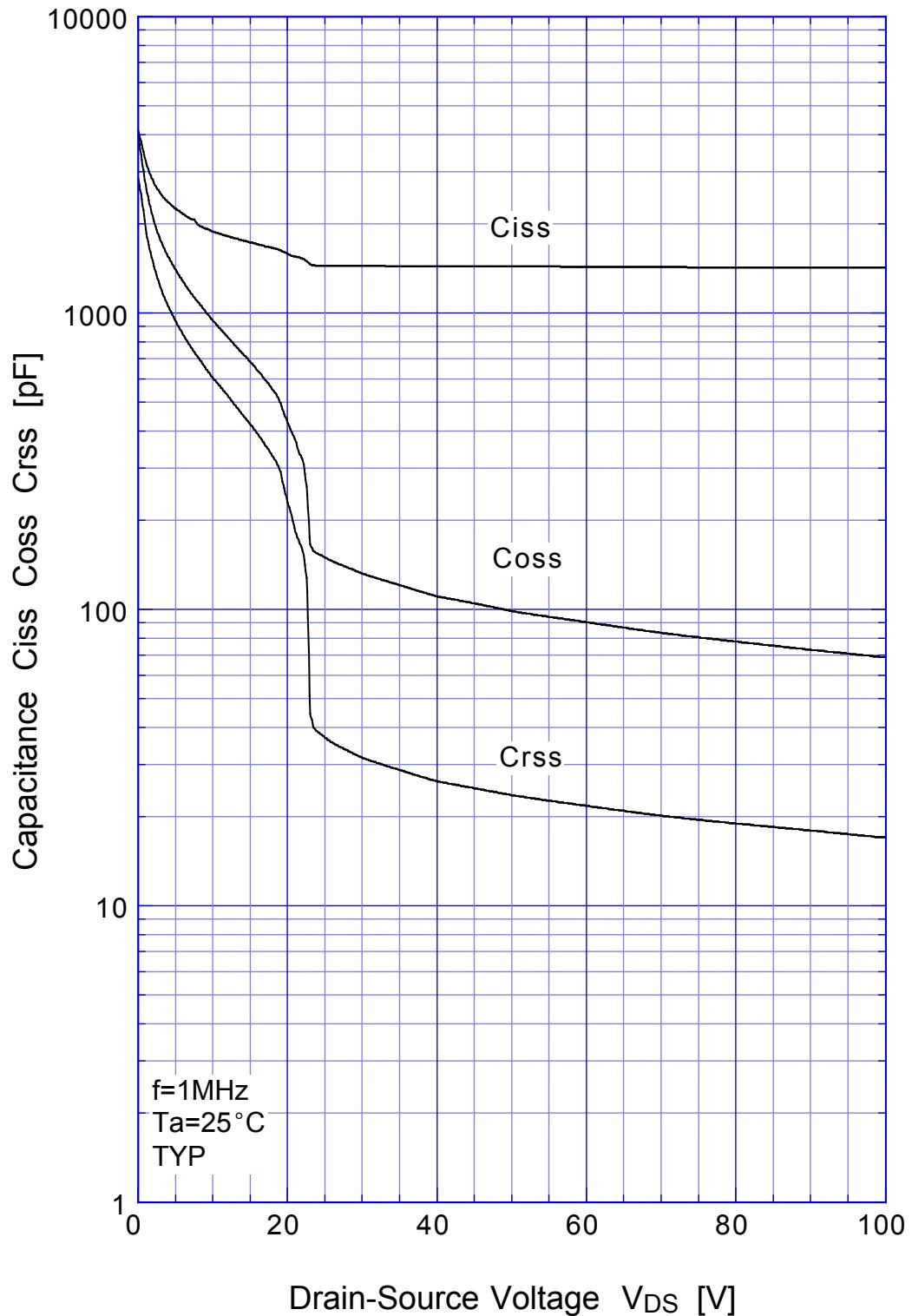
## 2SK2675 Transient Thermal Impedance



## **2SK2675 Single Avalanche Energy Derating**

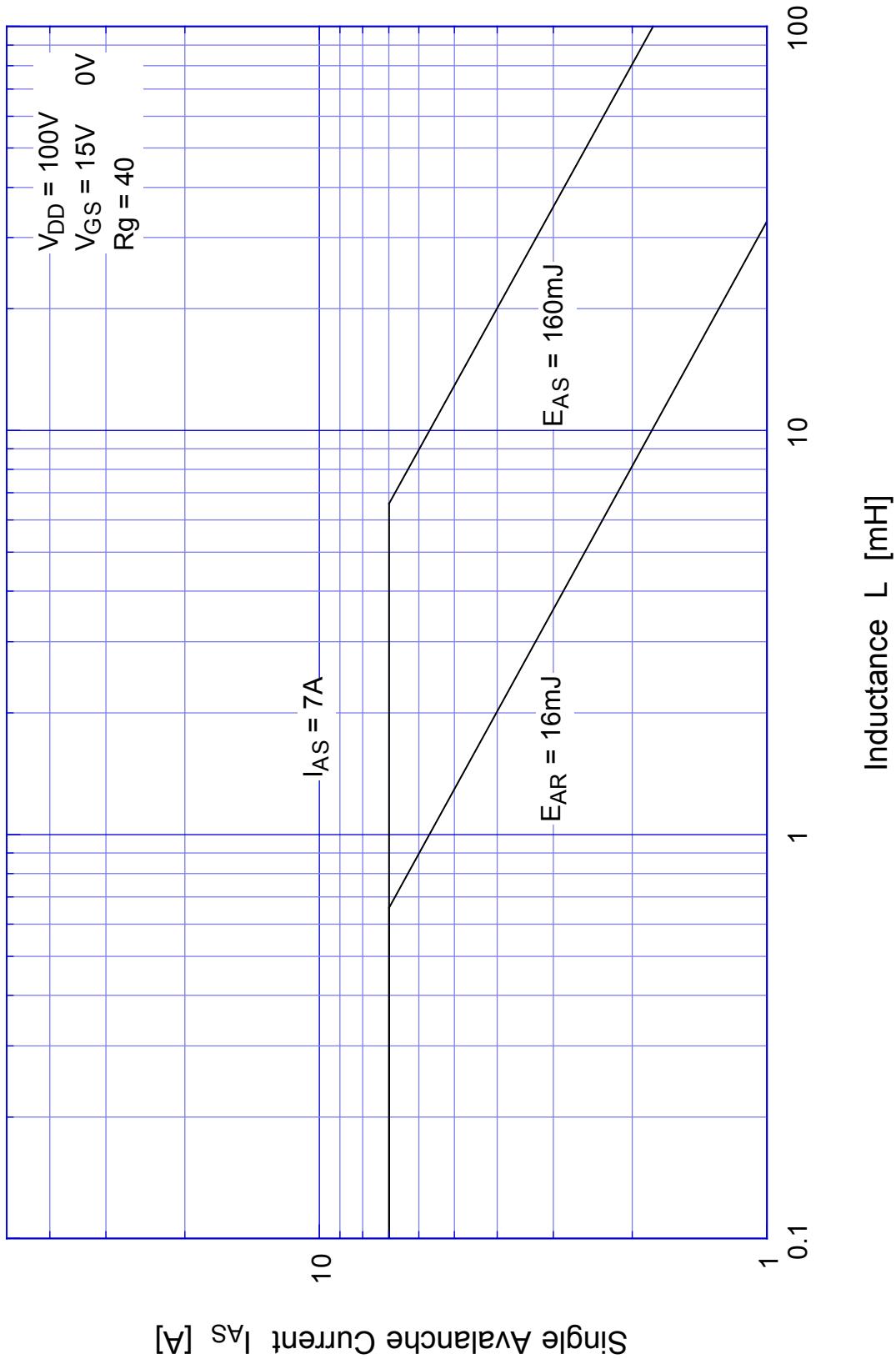


2SK2675 Capacitance



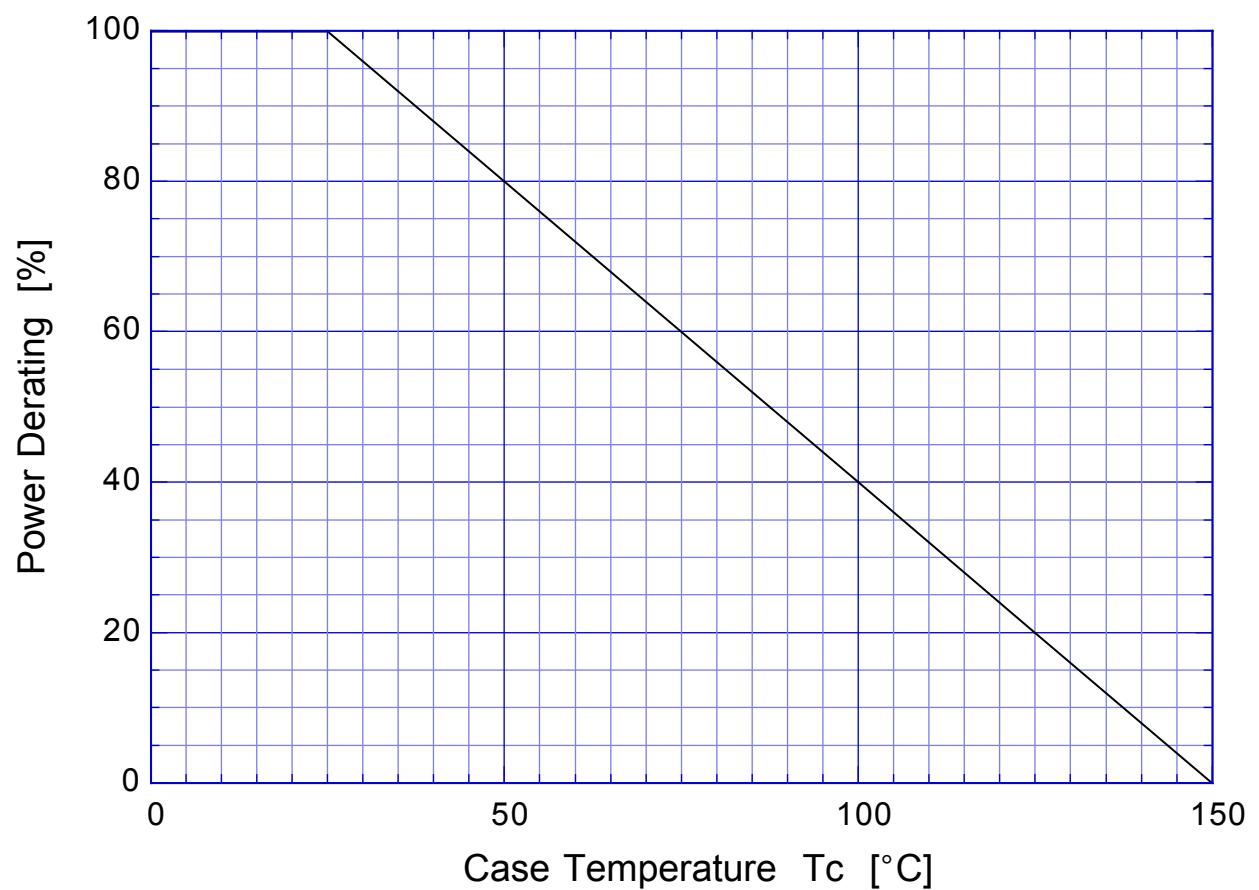
## 2SK2675 Single Avalanche Current - Inductive Load

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**2SK2675**

Power Derating



# 2SK2675

## Gate Charge Characteristics

